

Overview

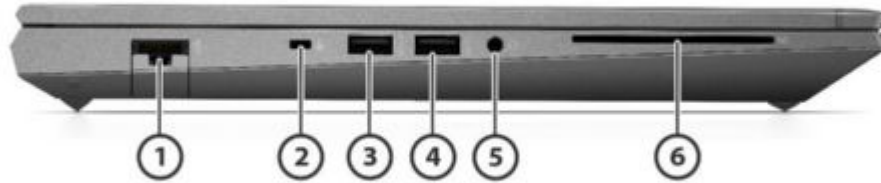
HP ZBook Fury 15 G7 Mobile Workstation



Right

- | | |
|--|--|
| 1. Ambient Light Sensor | 13. Fingerprint Sensor (optional) |
| 2. Internal Microphones (optional) | 14. Touchpad |
| 3. Camera LEDs (optional) | 15. 3-button Touchpad |
| 4. Camera (optional) | 16. Indicator LEDs: Power light, Wireless light, Storage usage light |
| 5. IR Camera (optional) | 17. Power connector |
| 6. Camera Cover (optional) | 18. USB Type-C® with Thunderbolt™ |
| 7. Speakers with Discrete Amplifier | 19. USB Type-C® with Thunderbolt™ |
| 8. Function Keys (changes with configured options) | 20. Mini DisplayPort™ |
| 9. Power button | 21. HDMI port |
| 10. HP Programmable Key | 22. SD Card Reader |
| 11. Numeric Keypad | |
| 12. Pointstick | |

Overview



Left

- | | |
|--------------------------------|----------------------|
| 1. RJ-45 | 4. USB 3.1 Gen 1 |
| 2. Nano security lock slot | 5. Audio Combo Jack |
| 3. USB 3.1 Gen 1 Charging Port | 6. Smart Card Reader |

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro ¹, powered by HP's collaboration and connectivity technology.
- Accelerate your workflow. Power through projects with up to 128 GB RAM ² for fast rendering, editing and visual effects performance.
- Take multitasking to the next level with the Intel® Core™ i9 processor ³ designed to handle complex, multithreaded apps like Adobe® Premier Pro, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.⁴
- Run demanding professional apps with the newest generation Intel® Xeon® processors ⁵ for powerful performance and productivity.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Turing architecture with Quadro® T-Series and RTX graphics¹⁹; Certified and supported for the apps you use every day.
- Strenuously tested to meet software certification and deliver superb performance with leading software providers, including Autodesk and Adobe® ⁶.
- Blitz through multiple tasks and ditch external drives with up to 8 TB ⁷, local PCIe NVMe storage - up to 21x faster than standard HDD and 6x faster than SATA SSD ⁹.
- Have confidence with the HP's most secure mobile workstations. Instantly protect against visual hacking with HP Sure View ¹⁰ and defend against firmware and malware attacks with HP Sure Start ¹¹ and HP Sure Sense ¹², and have peace of mind with multi-factor authentication- including an infrared camera and fingerprint scanner ¹³.
- Enhanced transfer and upload speeds via dual Thunderbolt™ 3 ports. Get wide-ranging connectivity options to ensure maximum device interaction: USB 3.0, HDMI, mDP, SD card, Smart Card Reader and more.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H ¹⁴ tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 3 ¹⁵ transfers and the flexibility to run up to two external 4K displays ^{16,17}.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges ¹⁸.

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² Up to 128GB nECC memory is an optional, configurable feature.

³ Multicore is designed to improve performance of certain software products. Not all customers or software applications will

Overview

necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance

⁴ Adobe Premier Pro and Autodesk 3ds Max sold separately.

⁵ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance

⁶ Adobe and Autodesk software sold separately.

⁷ For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 3GB (for Windows 10) of system drive is reserved for system recovery software.

⁹ Speeds based on 8TB PCIe NVMe storage.

¹⁰ Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.

¹¹ HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.

¹² HP Sure Sense requires Windows 10. See product specifications for availability.

¹³ Infrared camera and fingerprint scanner are optional, configurable features.

¹⁴ Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

¹⁵ HP Thunderbolt Dock with Thunderbolt™ 3 sold separately.

¹⁶ External displays sold separately.

¹⁷ Optional hybrid graphics is required to run up to two external 4K displays.

¹⁸ Based on internal testing vs. previous generation product with 802.11ac wireless LAN module.

¹⁹ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

| | |
|--------------------------|---|
| Preinstalled OS | Windows 10 Pro 64 - HP recommends Windows 10 Pro for business. ¹ Windows 10 Pro for Workstations 64 ¹ Windows 10 Home 64 ¹ Windows 10 Home Single Language 64 ¹ FreeDOS 3.0 |
| Web support OS | Red Hat® Enterprise Linux® 8 ² Ubuntu Linux 18.04 ² Windows 10 Enterprise 64 ¹ |
| Supported Version | HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282 . |

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² For detailed Linux® OS/hardware support information, see: http://www.hp.com/linux_hardware_matrix

PROCESSOR

10th Generation Intel® Xeon® W-10885M vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i9-10885H vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i7-10850H vPro™ with Intel® UHD Graphics (2.7 GHz base frequency, up to 5.1 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i7 10750H with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)^{1,2,3,4,5}

10th Generation Intel® Core™ i5-10400H vPro™ with Intel® UHD Graphics (2.6 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i5 10300H with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.5 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{1,2,3,4,5}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

⁵ For full Intel® vPro® functionality, Windows, a vPro supported processor, vPro enabled Q370 chipset or higher and vPro enabled WLAN card are required. Some functionality, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.

Features

CHIPSET

Mobile Intel® WM 490

INTEL® CORE™ I5 WITH VPRO/CORE™ I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ and Xeon® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. ^{1,2}

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VP corporate network connection which is either cable or wireless LAN.

² Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Core™ i9 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Core™ i9 with vPro™/XEON® with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Integrated

Intel® UHD Graphics ^{1,2,3,4,5}

Discrete

NVIDIA Graphic options:

NVIDIA® Quadro® RTX 5000 with Max-Q Design (16 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

NVIDIA® Quadro® RTX 4000 with Max-Q Design (8 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

NVIDIA® Quadro® RTX 3000 (6 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

NVIDIA® Quadro® T2000 with Max-Q Design (4 GB GDDR6 dedicated) ^{1,2,3,4,5}

NVIDIA® Quadro® T1000 with Max-Q Design (4 GB GDDR6 dedicated) ^{1,2,3,4,5}

AMD Graphic options:

AMD Radeon Pro W5500M (4 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

AMD Radeon RX 5500M (4 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

¹ UHD content required to view UHD images.

² Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

³ HDMI cable Sold Separately

⁴ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁵ miniDP cable sold separately.

⁶ GPU configurations may be limited to specific panel options

Features

⁷ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

DISPLAY

Non-touch

- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 250 nits 45% CG^{1,2}
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% CG^{1,2}
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% CG Next Gen HP SureView Reflect^{1,2,5}
- 15.6" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 anti-glare BV LED-backlit and ambient light sensor 600 nits 100% DCI-P3 Next Gen HP Dream Color display^{1,2,3,4}

Touch

- 15.6" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 600 nits 100% DCI-P3^{1,2,3,4}

HP Virtual Reality⁶ Headset (sold separately)

- HP Reverb
- HP Reverb G2

¹ UHD content required to view UHD images.

² Resolutions are dependent upon monitor capability, and resolution and color depth settings.

³ Display options may be limited to specific GPU Configurations.

⁴ VESA DisplayHDR 400 certifications are pending.

⁵ HP Sure View Reflect is optional and must be configured at purchase.

⁶ Virtual Reality content is required to view Virtual Reality images

STORAGE AND DRIVES*

Max Storage

8TB through four M.2 NVMe drives

6TB through two M.2 NVMe drives and one 2.5" SATA drive

(up to 1) HDD Storage (SATA 3.2)

500 GB 7200 rpm SATA FIPS 140-2 SED HDD

500 GB 7200 rpm SATA HDD

1 TB 7200 rpm SATA HDD

2 TB 5400 rpm SATA HDD

(up to 4) M.2 Storage (NVMe™ PCIe SSD)

256 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive

512 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive

256 GB PCIe (NVMe™) TLC Solid State Drive

512 GB PCIe (NVMe™) TLC Solid State Drive

1 TB PCIe (NVMe™) TLC Solid State Drive³

2 TB PCIe (NVMe™) TLC Solid State Drive³

²Storage slot 1-4 can support NVMe protocol

³Storage slot 1, 3 and 4 can support SATA protocol

Features

⁴Only storage slots 1-3 can support RAID

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)

PCIe Gen 3 x 4 lanes NVMe Solid State Drive

RAID:

RAID 0 and RAID 1 support¹

¹ Support only available with 1TB + 1TB M.2 storage or 2TB + 2TB M.2 storage combinations

² Not available if slots if storage slots 3 or 4 are selected

MEMORY

Maximum Memory^{3,2,5}

128 GB DDR4-2667 non-ECC SDRAM

64 GB DDR4-2667 ECC SDRAM

4 DDR4 SODIMMS⁴

Supports Dual Channel Memory¹

Slots are customer accessible / upgradeable

¹Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

² Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

³Transfer rates up to 2667 MT/s for nECC and ECC memory combinations when memory suppliers are consistent. If suppliers are not consistent, speeds may drop to 2133 MT/s for nECC and 2400 MT/s for ECC memory combinations. A custom configuration including part number AY104AV can be used to lock in a consistent vendor.

⁴ Intel® allows architectures designed with four DIMM slots to run at 2400 MT/s

⁵ Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NETWORKING/COMMUNICATIONS

LAN

Intel® I219-LM GbE, vPro™¹

Intel® I219-V GbE, non-vPro™¹

¹GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro™¹

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro™¹

¹Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

WWAN¹

Features

Intel® XMM™ 7360 LTE Advanced CAT 9

¹ WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone dual array digital microphone¹, functions keys for volume up and down, combo microphone/headphone jack, HD audio

¹Dual-microphone array when equipped with optional webcam and optional world facing microphone.

Camera^{1, 2, 3}

720p HD webcam with IR

720p HD webcam

¹ FHD and HD content required to view HD images respectively.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

³Camera-configured options come with a Privacy Shutter

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, a Programmable Key, with sperate numeric keypad, HP DuraKey, touchpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices

Dual pointstick; Touchpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: <http://www.hp.com/go/isv>

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: <http://www.hp.com/go/RGS>

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP

Features

Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to use requirements. Download at: <http://www.hp.com/go/performanceadvisor>

Software

Bing search for IE11
Buy Office
HP Hotkey Support
HP Image Assistant
HP Noise Cancellation Software
HP Performance Advisor⁸
HP Sure Recover
HP ZCentral Remote Boost²
HP Support Assistant^{1,7}
Native Miracast support⁴
HP Connection Optimizer⁹
HP Cloud Recovery
myHP

Security Management

Absolute persistence module⁶

HP Admin

HP Device Access Manager
HP FingerPrint Sensor
HP Manageability Integration Kit Gen4¹¹
HP Power On Authentication
Security lock slot¹²
Trusted Platform Module TPM 2.0 Embedded Security Chip with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2 Level Certified)
Master Boot Record security
Pre-boot authentication
Windows Defender¹⁰
HP Client Security Manager Gen5^{7, 16}
HP BIOSphere Gen6⁵
HP Sure Recover Gen3¹³
HP Sure Start Gen6^{5, 14}
HP Secure Erase¹⁵
HP Sure Sense¹⁷
HP Secure Platform¹⁸
HP Sure Click
HP Sure Run Gen3
HP Tamper Lock
HP SureView Reflect
Smartcard Reader - Alcor AU9560 (FIPS 201 Compliant)

For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

¹ HP Support Assistant - Requires Windows and Internet Access.

² HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.⁴ Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>.

⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations. ⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: <http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

Features

- ⁸ HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: <https://www8.hp.com/us/en/workstations/performance-advisor.html>
- ⁹ HP Connection Optimizer requires Windows 10.
- ¹⁰ Microsoft Defender Opt in and internet connection required for updates.
- ¹¹ HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.
- ¹² Nano Security lock slot is Lock sold separately.
- ¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
- ¹⁴ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.
- ¹⁵ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- ¹⁶ HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
- ¹⁷ HP Sure Sense requires Windows 10. See product specifications for availability.
- ¹⁸ Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

POWER

Power Supply

Up to 16 hours 15 minutes¹

HP Long Life 8-cell, 94 Wh Li-ion polymer²

120 W Slim Smart external AC power adapter

150 W Slim Smart external AC power adapter

200 W UltraSlim Smart external AC power adapter

120 W power adapter is configurable with Intel UMA graphics

150 W power adapter is configurable with NVIDIA Quadro T1000 and T2000 configurations

200 W power adapter is configurable with NVIDIA Quadro RTX 3000³ or higher configurations

¹ Measured with MobileMark 14

² Serviceable by warranty. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year.

³ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® 2.0 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country.¹

Low halogen²

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

35.7 x 24.25 x 2.59 cm

14.06 x 9.55 x 1.02 in

Weights

Starting at 2.35kg (5.18 lb)

Weight varies by configuration and components.

A deck: Anodized Aluminum

B deck: Aluminum with plastic antenna cover; Touch has Corning® Gorilla® Glass 5

C deck: Anodized Aluminum

D deck: Magnesium Die Cast

E door: Magnesium Die Cast

Metal Alloy Hinges

PORTS/SLOTS

1 smart card reader

1 SD 4.0 Media Card Reader

Left side⁶

1 RJ-45

1 USB 3.1 Gen 1 (charging)

1 USB 3.1 Gen 1

1 headphone/microphone combo

Right side⁶

1 power connector

2 USB Type-C® (Thunderbolt™ 3, pass through support DisplayPort™ 1.4², USB 3.1 Gen 2, with BC 1.2)

1 Mini DisplayPort™ 1.4

1 HDMI 2.0b^{1,3,4,5}

¹ HDMI port-cable not included.

² Mini DisplayPort™ 1.4 with discrete, 1.2 with UMA.

³ HDMI 2.0b with discrete, 1.4 with UMA.

⁴ When both USB Type-C® are in use, HDMI cannot be detected

⁵ When one USB Type-C® is in use, HDMI can be detected if USB Type-C® in use is assigned to different channel

⁶ When product is under heavy power loading, performance may be reduced to prevent battery drain. Disconnecting USB device will restore system performance

Features

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

Technical Specifications – System Unit

SYSTEM UNIT

| | | | |
|--|---|---|-------------------------------|
| Stand-Alone Power Requirements (AC Power) | Nominal Operating Voltage | 19.5V | |
| | Average Operating Power(idle) | System in idle mode + max panel brightness | Adapter Safety test condition |
| | Discrete Graphics | 80W | |
| Temperature | Max Operating Power | <200W | |
| | Operating | 41° to 122° F (5° to 50° C) (reading optical) '41° to 113° F (5° to 45° C) (writing optical) | |
| | Non-operating | 40° to 140° F (-40° to 60° C) | |
| Relative Humidity | Operating | 10% to 90%, non-condensing | |
| | Non-operating | 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature | |
| Shock | Operating | 40 G, 2 ms, half-sine | |
| | Non-operating | 200 G, 2 ms, half-sine | |
| Random Vibration | Operating | 0.75 grms | |
| | Non-operating | 1.50 grms | |
| Maximum Altitude (unpressurized) | Operating | -50 to 10,000 ft. (-15.24 to 3,048 m) | |
| | Non-operating | -50 to 15,000 ft. (-15.24 to 12,192 m) | |
| Planned Industry Standard Certifications | UL | Yes | |
| | CSA | Yes | |
| | FCC Compliance | Yes | |
| | ENERGY STAR® | Yes | |
| | EPEAT® | Yes | |
| | ICES | Yes | |
| | Australia / NZ A-Tick Compliance | Yes | |
| | CCC | Yes | |
| | Japan VCCI Compliance | Yes | |
| | KCC | Yes | |
| | BSMI | Yes | |
| | CE Marking Compliance | Yes | |
| | MIL STD 810H | Yes | |
| | BNCI or BELUS | Yes | |
| | GOST | Yes | |
| Saudi Arabian Compliance (ICCP) | Yes | | |
| UKRSERTCOMPUTER | Yes | | |

¹Configurations of the HP ZBook Fury 15 G7 that are ENERGY STAR® qualified are identified as HP ZBook Fury 15 G7 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

²EPEAT® registered where applicable. EPEAT registration varies by country. See <http://www.epeat.net> for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.

Technical Specifications – Displays

DISPLAYS

| | | | | |
|---|-----------------------------------|--------------------------|-------------------|--|
| 15.6" diagonal FHD IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 250 nits 45% CG (1920 x 1080) | Outline Dimensions (W x H) | 399.95 x 251.01 mm (max) | | |
| | Active Area | 381.89 x 214.81 mm | | |
| | Weight | 550 g (max) | | |
| | Diagonal Size | 15.6 inch | | |
| | Thickness | 4.0 mm (max) | | |
| | Interface | eDP 1.2 | | |
| | Panel Technology | IPS | | |
| | Surface Treatment | Anti-Glare | | |
| | Touch Enabled | No | | |
| | Refresh Rate | 60 hrz | | |
| | Brightness | 400 nits | | |
| | Pixel Resolution | Format | 1920 x 1080 (FHD) | |
| | | Configuration | RGB | |
| | Backlight | LED | | |
| | PPI | 127 | | |
| | Color Gamut Coverage | 45% CG | | |
| Color Depth | 6 bits + Hi FRC | | | |
| Viewing Angle | UWVA 85/85/85/85 | | | |

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

| | | | | |
|---|-----------------------------------|--------------------------|-------------------|--|
| 15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% CG (1920 x 1080) | Outline Dimensions (W x H) | 399.95 x 251.01 mm (max) | | |
| | Active Area | 381.89 x 214.81 mm | | |
| | Weight | 550 g (max) | | |
| | Diagonal Size | 15.6 inch | | |
| | Thickness | 4.0 mm (max) | | |
| | Interface | eDP 1.3 + PSR | | |
| | Panel Technology | IPS | | |
| | Surface Treatment | Anti-Glare | | |
| | Touch Enabled | No | | |
| | Refresh Rate | 60 hrz | | |
| | Brightness | 400 nits | | |
| | Pixel Resolution | Format | 1920 x 1080 (FHD) | |
| | | Configuration | RGB | |
| | Backlight | LED | | |
| | PPI | 127 | | |
| | Color Gamut Coverage | 72% CG | | |

Technical Specifications – Displays

| | |
|----------------------|------------------|
| Color Depth | 6 bits + Hi FRC |
| Viewing Angle | UWVA 85/85/85/85 |

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Next Gen HP SureView Reflect 15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% CG (1920 x 1080)

| | | |
|-----------------------------------|---|-------------------|
| Outline Dimensions (W x H) | 398.6 x 253 mm (max) (w/ bracket & PCB) | |
| Active Area | 382.12 x 214.94 mm | |
| Weight | 550 g (max) | |
| Diagonal Size | 15.6 inch | |
| Thickness | 4.0 mm (max) | |
| Interface | eDP 1.3 + PSR | |
| Panel Technology | IPS | |
| Surface Treatment | Anti-Glare | |
| Touch Enabled | No | |
| Contrast Ratio | 1000:1 (typ.) | |
| Refresh Rate | 60Hz | |
| Brightness | 1000 nits | |
| Pixel Resolution | Pitch | 1920 x 1080 (FHD) |
| | Format | RGB |
| Backlight | LED | |
| PPI | 254 | |
| Color Gamut Coverage | 72% CG | |
| Color Depth | 8 bits | |
| Viewing Angle | UWVA 85/85/85/85 | |

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Next Gen HP Dream Color display 15.6" diagonal UHD IPS HDR 400 eDP1.4 + PSR2 anti-glare BV LED-backlit and ambient light sensor 600 nits 100% DCI-P3 (3840 x 2160)

| | | |
|-----------------------------------|---|-------------------|
| Outline Dimensions (W x H) | 398.6 x 253 mm (max) (w/ bracket & PCB) | |
| Active Area | 382.12 x 214.94 mm | |
| Weight | 550 g (max) | |
| Diagonal Size | 15.6 inch | |
| Thickness | 4.0 mm (max) | |
| Interface | eDP 1.4 + PSR2 | |
| Panel Technology | IPS | |
| Surface Treatment | Anti-Glare | |
| Touch Enabled | No | |
| Contrast Ratio | 1000:1 (typ.) | |
| Refresh Rate | 60Hz | |
| Brightness | 600 nits | |
| Pixel Resolution | Pitch | 3840 x 2160 (UHD) |
| | Format | RGB |
| Backlight | LED | |

Technical Specifications – Displays

| | |
|-----------------------------|------------------|
| PPI | 254 |
| Color Gamut Coverage | 100% DCI-P3 |
| Color Depth | 8 bits |
| Viewing Angle | UWVA 85/85/85/85 |

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal UHD IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 600 nits 100% DCI-P3 (3840 x 2160)

| | | |
|-----------------------------------|---|-------------------|
| Outline Dimensions (W x H) | 398.6 x 253 mm (max) (w/ bracket & PCB) | |
| Active Area | 382.12 x 214.94 mm | |
| Weight | 550 g (max) | |
| Diagonal Size | 15.6 inch | |
| Thickness | 4.0 mm (max) | |
| Interface | eDP 1.4 + PSR2 | |
| Panel Technology | IPS | |
| Surface Treatment | Gorilla Glass 5 with Anti-Glare | |
| Touch Enabled | No | |
| Contrast Ratio | 1000:1 (typ.) | |
| Refresh Rate | 60Hz | |
| Brightness | 600 nits | |
| Pixel Resolution | Pitch | 3840 x 2160 (UHD) |
| | Format | RGB |
| Backlight | LED | |
| PPI | 254 | |
| Color Gamut Coverage | 100% DCI-P3 | |
| Color Depth | 8 bits | |
| Viewing Angle | UWVA 85/85/85/85 | |

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Anti-Glare surface treatment only available with non-touch option

Technical Specifications – Storage

STORAGE AND DRIVES

| | | | | |
|---|------------------------------|--|---------------------------------|--|
| 256GB PCIe NVMe TLC M.2 2280 Solid State Drive | Form Factor | M.2 2280 | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 256GB | | |
| | Generation | 1100 | | |
| | NAND Type | TLC | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 3500 MB/s | 2200 MB/s | |
| | Logical Blocks | 1,000,215,216 | | |
| | Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | |
| | Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | |

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

| | | | | |
|--|------------------------------|--|---------------------------------|--|
| 256GB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive | Form Factor | M.2 2280 | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 256GB | | |
| | Generation | 1100 | | |
| | NAND Type | TLC | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 3000 MB/s | 1600 MB/s | |
| | Logical Blocks | 1,000,215,216 | | |
| | Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | |
| | Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | |

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Storage

| | | | | |
|---|------------------------------|--|---------------------------------|--|
| 512GB PCIe NVMe TLC M.2 2280 Solid State Drive | Form Factor | M.2 2280 | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 512GB | | |
| | Generation | 1100 | | |
| | NAND Type | TLC | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 3400 MB/s | 2956 MB/s | |
| | Logical Blocks | 1,000,215,216 | | |
| | Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | |
| | Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | |

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

| | | | | |
|--|------------------------------|--|---------------------------------|--|
| 512TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive | Form Factor | M.2 2280 | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 512GB | | |
| | Generation | 1100 | | |
| | NAND Type | TLC | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 3400 MB/s | 2500 MB/s | |
| | Logical Blocks | 1,000,215,216 | | |
| | Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | |
| | Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | |

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Storage

| | | | | |
|---|--|--------------------------------|---------------------------------|--|
| 1TB PCIe NVMe TLC M.2 2280 Solid State Drive | Form Factor | M.2 2280 | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 1TB | | |
| | NAND Type | TLC | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 3480 MB/s | 2800 MB/s | |
| | Logical Blocks | 1,000,215,216 | | |
| Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | | |
| Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | | |
| Available in RAID 1 config | Yes | | | |

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

| | | | | |
|---|--|--------------------------------|---------------------------------|--|
| 2TB PCIe NVMe TLC M.2 2280 Solid State Drive | Form Factor | M.2 2280 | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 2TB | | |
| | NAND Type | TLC | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 3180 MB/s | 2920 MB/s | |
| | Logical Blocks | 1,000,215,216 | | |
| Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | | |
| Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | | |
| Available in RAID 1 config | Yes | | | |

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Storage

| | | | | |
|----------------------------|------------------------------|--|---------------------------------|--|
| 500GB SATA 2.5" HDD | Form Factor | 2.5" | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 500GB | | |
| | Generation | 1100 | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 530 | 400 | |
| | Logical Blocks | 1,000,215,216 | | |
| | Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | |
| | Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | |

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

| | | | | |
|---|------------------------------|--|---------------------------------|--|
| 500GB SATA 2.5" SED HDD - FIPS-140-2 | Form Factor | 2.5" | | |
| | Drive Weight | 0.02 lb (10 g) | | |
| | Capacity | 500GB | | |
| | Generation | 1100 | | |
| | Height | 2.6 mm Max | | |
| | Width | 0.87 in (22 mm) | | |
| | Interface | ACS-3, SATA 3.2 | | |
| | Performance | Maximum Sequential Read | Maximum Sequential Write | |
| | | 530 | 400 | |
| | Logical Blocks | 1,000,215,216 | | |
| | Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | | |
| | Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | | |

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Storage

1TB SATA 2.5" HDD

| | | |
|------------------------------|--|---------------------------------|
| Form Factor | 2.5" | |
| Drive Weight | 0.02 lb (10 g) | |
| Capacity | 1TB | |
| Generation | 1100 | |
| Height | 2.6 mm Max | |
| Width | 0.87 in (22 mm) | |
| Interface | ACS-3, SATA 3.2 | |
| Performance | Maximum Sequential Read | Maximum Sequential Write |
| | 530 | 400 |
| Logical Blocks | 1,000,215,216 | |
| Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | |
| Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | |

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

2TB SATA 2.5" HDD

| | | |
|------------------------------|--|---------------------------------|
| Form Factor | 2.5" | |
| Drive Weight | 0.02 lb (10 g) | |
| Capacity | 2TB | |
| Generation | 1100 | |
| Height | 2.6 mm Max | |
| Width | 0.87 in (22 mm) | |
| Interface | ACS-3, SATA 3.2 | |
| Performance | Maximum Sequential Read | Maximum Sequential Write |
| | 530 | 400 |
| Logical Blocks | 1,000,215,216 | |
| Operating Temperature | 32° to 158°F (0° to 70°C) [ambient temp] | |
| Features | ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP | |

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Networking

NETWORKING/COMMUNICATION

| | | |
|--|-------------------------------------|--|
| Intel i219LM 10/100/1000 Integrated NIC | Connector | RJ-45 |
| | System Interface | PCI(Intel proprietary) + SMBus |
| | Data rates supported | 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s |
| | IEEE Compliance | IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) |
| | Performance | TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K |
| | Power consumption | Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW |
| | Power Management | ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption |
| | Management Interface | Auto MDI/MDIX Crossover cable detection |
| | IT Manageability | Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status |
| | Security & Manageability | Intel® vPro™ support with appropriate Intel® chipset components |

Technical Specifications – Networking

| | | |
|---|-----------------------------|--|
| Intel i219v 10/100/1000 Integrated NIC | Connector | RJ-45 |
| | System Interface | PCI(Intel proprietary) + SMBus |
| | Data rates supported | 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s |
| | IEEE Compliance | IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) |
| | Performance | TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K |
| | Power consumption | Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW |
| | Power Management | ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption |
| | Management Interface | Auto MDI/MDIX Crossover cable detection |
| | IT Manageability | Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status |

Technical Specifications – Networking

NFC (Near Field Communication) module (optional)

| | | |
|--|---|----------------------------|
| Dimensions (L x W x H) | Module 50 mm by 23 mm by 2.89 mm | |
| Chipset | SiM3U156+SiM3U154+AMS3911 | |
| System interface | USB 2.0 | |
| System interface (I/O) | Audio signal output on card read | |
| NFC RF standards (In reading CSN) | ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 | |
| NFC Forum Support | Tag Type 1, Type 2, Type3 and Type 4 in reading CSN | |
| Reader Mode | 13.56MHz: ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Topaz cards HID iClass ISO 125kHz: HID Prox UID AWID UID CASI-RUSCO UID EM 410x UID Indiana ASP/ASP+ UID | |
| Frequency | 13.56MHz and 125kHz | |
| NFC Modes Supported | Reader | |
| Raw RF Data Rates | 106, 212 kbps | |
| Operating temperature | -30°C to 70°C | |
| Storage temperature | -40°C to 80°C | |
| Humidity | 10-90% operating 5-95% non-operating | |
| Supply Operating voltage | 4.35 to 5.25 Volts | |
| Power Consumption | Mode | Power Consumption, Typical |
| | Polling | 75mA |
| | Communication | 85mA |
| Antenna | 13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin connector FPC. | |

| | | |
|---|-------------------------------|---------------|
| Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro | Wireless LAN Standards | IEEE 802.11a |
| | | IEEE 802.11b |
| | | IEEE 802.11g |
| | | IEEE 802.11n |
| | | IEEE 802.11ac |
| | | IEEE 802.11ax |

Technical Specifications – Networking

| | |
|------------------------------------|---|
| | IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v |
| Interoperability | Wi-Fi certified |
| Frequency Band | 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz |
| Data Rates | 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) |
| Modulation | Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM |
| Security¹ | IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI |
| Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) |
| Roaming | IEEE 802.11 compliant roaming between access points |
| Output Power² | 802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +15.5dBm minimum 802.11n HT40(5GHz) : +14.5dBm minimum 802.11ac VHT80(5GHz) : +11.5dBm minimum 802.11ac VHT160(5GHz) : +11.5dBm minimum 802.11ax HT40(2.4GHz) : +10dBm minimum 802.11ax VHT160(5GHz) : +10dBm minimum |
| Power Consumption | Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW |

Technical Specifications – Networking

| | | |
|--|--|--------------------------------|
| Power Management | ACPI and PCI Express compliant power management 802.11 compliant power saving mode | |
| Receiver Sensitivity³ | 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum | |
| Antenna Type | High efficiency antenna with spatial diversity, mounted in the display enclosure | |
| | Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications | |
| Form Factor | PCI-Express M.2 MiniCard with CNVi Interface | |
| Dimensions | 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm | |
| Weight | 1. Type 2230 : 2.8g 2. Type 126: 1.3g | |
| Operating Voltage | 3.3v +/- 9% | |
| Temperature | Operating | 14° to 158° F (-10° to 70° C) |
| | Non-operating | -40° to 176° F (-40° to 80° C) |
| Humidity | Operating | 10% to 90% (non-condensing) |
| | Non-operating | 5% to 95% (non-condensing) |
| Altitude | Operating | 0 to 10,000 ft (3,048 m) |
| | Non-operating | 0 to 50,000 ft (15,240 m) |
| LED Activity | LED Amber - Radio Off; LED Off - Radio ON | |
| HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology | | |
| Frequency Band | 2402 to 2480 MHz | |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) | |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) | |
| Transmit Power | The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR. | |
| Power Consumption | Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW | |
| Bluetooth Software Supported Link Topology | Microsoft Windows Bluetooth Software | |
| Power Management | Microsoft Windows ACPI, and USB Bus Support | |

Technical Specifications – Networking

| | |
|--|--|
| Certifications | FCC (47 CFR) Part 15C, Section 15.247 & 15.249 |
| Power Management Certifications | ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |

Intel Wi-Fi 6 AX201 + BT5 Wireless LAN Standards
(802.11ax 2x2, vPro, supporting gigabit file transfer speeds)
vPro

| | |
|-------------------------|--|
| IEEE 802.11a | |
| IEEE 802.11b | |
| IEEE 802.11g | |
| IEEE 802.11n | |
| IEEE 802.11ac | |
| IEEE 802.11ax | |
| IEEE 802.11d | |
| IEEE 802.11e | |
| IEEE 802.11h | |
| IEEE 802.11i | |
| IEEE 802.11k | |
| IEEE 802.11r | |
| IEEE 802.11v | |
| Interoperability | Wi-Fi certified |
| Frequency Band | 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz |
| Data Rates | 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) |

Technical Specifications – Networking

| | |
|---|---|
| Modulation | Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM |
| Security¹ | IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI |
| Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) |
| Roaming | IEEE 802.11 compliant roaming between access points |
| Output Power² | 802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +15.5dBm minimum 802.11n HT40(5GHz) : +14.5dBm minimum 802.11ac VHT80(5GHz) : +11.5dBm minimum 802.11ac VHT160(5GHz) : +11.5dBm minimum 802.11ax HT40(2.4GHz) : +10dBm minimum 802.11ax VHT160(5GHz) : +10dBm minimum |
| Power Consumption | Transmit mode :2.0 W Receive mode :1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode :50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW |
| Power Management | ACPI and PCI Express compliant power management 802.11 compliant power saving mode |
| Receiver Sensitivity³ | 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum |
| Antenna Type | High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications |
| Form Factor | PCI-Express M.2 MiniCard with CNVi Interface |
| Dimensions | 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm |
| Weight | 1. Type 2230 : 2.8g 2. Type 126: 1.3g |

Technical Specifications – Networking

| | |
|--|--|
| Operating Voltage | 3.3v +/- 9% |
| Temperature | Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C) |
| Humidity | Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing) |
| Altitude | Operating Non-operating 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m) |
| LED Activity | LED Amber - Radio OFF; LED White - Radio ON |
| HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology | |
| Frequency Band | 2402 to 2480 MHz |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) |
| Transmit Power | The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR. |
| Power Consumption | Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW |
| Bluetooth Software Supported Link Topology | Microsoft Windows Bluetooth Software |
| Power Management | Microsoft Windows ACPI, and USB Bus Support |
| Certifications | FCC (47 CFR) Part 15C, Section 15.247 & 15.249 |
| Power Management Certifications | ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |
| Security & Manageability | Intel® vPro™ support with appropriate Intel® chipset components |

Technical Specifications – Networking

Intel® XMM™ 7360 LTE-Advanced CAT9 (Pandora)*

| | |
|---|---|
| Technology/Operating bands | FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz |
| Wireless protocol standards | 3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification |
| GPS | Standalone, A-GPS (MS-A, MS-B) |
| GPS bands | 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz |
| Maximum data rates | LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) |
| Maximum output power | LTE: 23 dBm HSPA+: 23.5 dBm |
| Maximum power consumption | LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) |
| Form Factor | M.2, 3042-S3 Key B |
| Weight | 5.8 g |
| Dimensions (Length x Width x Thickness) | 42 x 30 x 2.3 mm |

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking

Near Field Communications Controller (optional)

| | | |
|---|--|---|
| Dimensions (L x W x H) | Module 25 mm by 10 mm by 2.0 mm | |
| Chipset | NPC100 | |
| System interface | I2C | |
| NFC RF standards | ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2 | |
| NFC Forum Support | Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 | |
| Reader (PCD-VCD) Mode(1) | ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards | |
| Card Emulation (PICC-VICC) Mode(1) | ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa | |
| Frequency | 13.56 MHz | |
| NFC Modes Supported | Reader/Writer, Peer-to-Peer | |
| Raw RF Data Rates | 106, 212, 424, 848 kbps | |
| Operating temperature | 0°C to 70°C | |
| Storage temperature | -20°C to 125°C | |
| Humidity | 10-90% operating 5-95% non-operating | |
| Supply Operating voltage | 4.35 to 5.25 Volts | |
| I/O Voltage | 1.8V or 3.3V | |
| Power Consumption | Booster enable, | VBAT= 3.3V, |
| | VCC_BOOST = 5V) | Polling 7.3 mA |
| | Mode Power Consumption, Typical | Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA |
| | | Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA |
| | | Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA |
| | | Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA |
| Antenna | Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module. | |

Technical Specifications – Power

POWER

| | | | |
|---------------------------------------|---|--|----------------------------------|
| 120 Watt Slim Smart AC Adapter | Dimensions | 138x68.5x25.4mm | |
| | Weight | unit: 350g +/- 10g | |
| | Input | Input Efficiency | 88% at 115 Vac and 89% at 230Vac |
| | | Input frequency range | 47 ~ 63 Hz |
| | | Input AC current | 1.7 A at 90 Vac and Maximum Load |
| | Output | Output power | 120W |
| | | DC output | 19.5V |
| | | Hold-up time | 5ms at 115 Vac input |
| | | Output current limit | <18.0A |
| | | Connector | C5 |
| | Environmental Design | Operating temperature | 32° to 95° F (0° to 35° C) |
| | | Non-operating (storage) temperature | -4° to 185° F (-20° to 85° C) |
| | | Altitude | 0 to 16,400 ft (0 to 5,000 m) |
| | | Humidity | 5% to 95% |
| Storage Humidity | | 5% to 95% | |
| EMI and Safety Certifications | Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. | | |

*Can only be configured with Intel UMA Graphics option

Technical Specifications – Power

| | | | |
|---------------------------------------|---|--|----------------------------------|
| 150 Watt Slim Smart AC Adapter | Dimensions | 138x66x22mm | |
| | Weight | unit: 325g +/- 10g | |
| | Input | Input Efficiency | 88% at 115 Vac and 89% at 230Vac |
| | | Input frequency range | 47 ~ 63 Hz |
| | | Input AC current | 2.7 A at 90 Vac and Maximum Load |
| | Output | Output power | 150W |
| | | DC output | 19.5V |
| | | Hold-up time | 5ms at 115 Vac input |
| | | Output current limit | <16.0A |
| | | Connector | C5 |
| | Environmental Design | Operating temperature | 32° to 95° F (0° to 35° C) |
| | | Non-operating (storage) temperature | -4° to 185° F (-20° to 85° C) |
| | | Altitude | 0 to 16,400 ft (0 to 5000m) |
| | | Humidity | 5% to 95% |
| Storage Humidity | | 5% to 95% | |
| EMI and Safety Certifications | Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. | | |

*Can only be configured with [Quadro T1000 and T2000 Graphics option](#)

| | | | |
|--|-----------------------------|--|----------------------------------|
| 200 Watt UltraSlim Smart AC Adapter | Dimensions | 152x73x23.5mm | |
| | Weight | unit: 530g +/- 10g | |
| | Input | Input Efficiency | 88% at 115 Vac and 89% at 230Vac |
| | | Input frequency range | 47 ~ 63 Hz |
| | | Input AC current | 2.9 A at 90 Vac and Maximum Load |
| | Output | Output power | 200W |
| | | DC output | 19.5V |
| | | Hold-up time | 5ms at 115 Vac input |
| | | Output current limit | <16.0A |
| | | Connector | C13 |
| | Environmental Design | Operating temperature | 32° to 95° F (0° to 35° C) |
| | | Non-operating (storage) temperature | -4° to 185° F (-20° to 85° C) |
| | | Altitude | 0 to 16,400 ft (0 to 5000m) |
| | | Humidity | 5% to 95% |

Technical Specifications – Power

Storage Humidity 5% to 95%

EMI and Safety Certifications

Eg:
 *CE Mark - full compliance with LVD and EMC directives
 * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV;
 Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
 * MTBF - over 100,000 hours at 25°C ambient condition.

*Can only be configured with Quadro RTX3000, RTX4000, RTX5000 Graphics and Radeon W5500M, RX 5500M Graphics option

HP Long Life 8-cell Polymer (94Wh) Battery

| | |
|--|---------------------------------------|
| Cells/Type | 8 cell |
| Energy | Voltage 11.55V |
| | Amp-hour capacity 4.15Ah |
| Temperature | Operating (Charging) 0° to 60° C |
| | Operating (Discharging) -20° to 70° C |
| Fuel Gauge LED | NA |
| Warranty | Depends on system offering |
| Optional Travel Battery Available | No |

* Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform.
 Refer to <http://www.hp.com/support/batterywarranty/> for battery warranty information.

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and marks labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status by country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test method)

| | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
|-------------------------------|--------------|--------------|--------------|
| Normal Operation (Short idle) | 7.38 W | 10.02 W | 7.29 W |
| Normal Operation (Long idle) | 4.94 W | 6.21 W | 4.87 W |
| Sleep | 1.69 W | 1.68 W | 1.59 W |
| Off | 0.41 W | 0.42 W | 0.41 W |

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. All HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not have ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured model featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

| | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
|-------------------------------|--------------|--------------|--------------|
| Normal Operation (Short idle) | 25.24 BTU/hr | 34.27 BTU/hr | 24.93 BTU/hr |
| Normal Operation (Long idle) | 16.89 BTU/hr | 21.24 BTU/hr | 16.66 BTU/hr |
| Sleep | 5.78 BTU/hr | 5.75 BTU/hr | 5.44 BTU/hr |
| Off | 1.4 BTU/hr | 1.44 BTU/hr | 1.4 BTU/hr |

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

| | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) |
|----------------------------------|--|---|
| Typically Configured - Idle | 2.6 | 14.2 |
| Fixed Disk - Random writes | 2.8 | 15.4 |
| Optical Drive - Sequential reads | 2.9 | 19.4 |

Longevity and Upgrading

"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- AC adapter
- Battery
- WLAN/WWAN module
- 4 storage slots (M.2 and HDD)
- 4 SODIMM memory slots

Technical Specifications – Environmental

Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

Mercury greater than 1ppm by weight

Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Battery description: 8 cell HP Long Life Polymer 94Wh (4.15Ah)

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 11.09% post-consumer recycled plastic (by wt.) *according to IEA 1680.1-2018 standard, criterion 4.2.1.1.*
- This product is 94.0% recycle-able when properly disposed of at end of life.

Packaging Materials

| | | |
|------------------|---|-------|
| External: | PAPER/Corrugated | 0.316 |
| | PAPER/Molded Pulp | 0.181 |
| Internal: | PLASTIC/Polyethylene low density - LDPE | 0.010 |
| | PLASTIC/Polypropylene - PP | 0.005 |

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 12.6% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend our restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances including PVC, BFRs, and certain phthalates in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see [HP RoHS position statement](#)

Technical Specifications – Environmental

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (reference General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants - may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel - finishes must not be used on the external surface designed to be frequently handled and carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic regions. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers to integrate and re-sell HP equipment.

HP Inc. Corporate Environmental

For more information about HP's commitment to the environment:

Technical Specifications – Environmental

Information

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

Options and Accessories (sold separately and availability may vary by country)

| Type | Description | Part # |
|--------------------------------|---|-------------|
| Displays | HP Z32 31.5" 4k UHD Display | 1AA81A8#XXX |
| | HP Z38c 37.5" Curved Display | Z4W65A8#XXX |
| Case | HP Essential Top Load Case (up to 15.6") | H2W17AA |
| | HP Essential Backpack (up to 15.6") | H1D24AA |
| | HP Exec 17.3 Midnight Backpack | 1KM17AA |
| | HP Business Case(up to 15.6") | 2SC66AA |
| | HP Executive 15.6 Midnight Top Load | 1KM15AA |
| | HP Exec 15.6 Midnight Backpack | 1KM16AA |
| | HP Executive 15.6 Black Leather Top Load | 1LG83AA |
| Docking Accessories | HP Adjustable Dual Monitor Stand | AW664AA |
| | HP Adjustable Display Stand | AW663AA |
| | HP Display and Notebook Stand II | E8G00AA |
| | HP Monitor Stand | M9X76AA |
| | HP Dual Hinge II Notebook Stand | E8F99AA |
| | HP Hot Desk Stand (up to 32" monitor) | W3Z73AA |
| | HP Hot Desk Stand Monitor Arm (for use with W3Z73AA; supports two 24" monitors) | W3Z74AA |
| | HP TB Audio Module (comp with Hook dock) | 3AQ21AA |
| | HP TB Dock G2 Combo Cable (this is 230W) comp with Hook dock | 3XB96AA |
| Docking station | HP USB-C Mini Dock - power not supported on mWKS | 1PM64AA |
| | HP TB Dock G2 w/ Combo Cable (this is 230W) | 3TR87AA |
| | HP Thunderbolt Dock 230W G2 | 2UK38AA |
| | HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations | 5TW13AA |
| | HP USB-C Dock G5 Power Not Supported on Mobile Workstation | 5TW10AA |
| Input/Output - Mice | HP Comfort Grip Wireless Mouse (See Link 5 Tab) | H2L63AA |
| | HP 3-button USB Laser Mouse | H4B81AA |
| | HP Bluetooth Travel Mouse | 6SP30AA |
| | HP USB Travel Mouse | G1K28AA |
| | HP Wireless Premium Mouse (See Link 5 Tab) | 1JR31AA |
| | HP Elite Presenter Mouse | 2CE30AA |
| Input/Output - Keyboard | HP Slim USB Keyboard and Mouse | T6T83AA |
| | HP Slim Wireless Keyboard and Mouse | T6L04AA |
| Input/Output - Adapter | HP USB-C to USB-A Hub | Z6A00AA |
| | HDMI to VGA Adapter | H4F02AA |
| | HP HDMI to DVI Adapter | F5A28AA |

Options and Accessories (sold separately and availability may vary by country)

| | | |
|----------------------------|--------------------------------------|---------|
| | HP USB-C to USB 3.0 Adapter | N2Z63AA |
| | HP USB-C to DisplayPort Adapter | N9K78AA |
| | HP USB-C to VGA Adapter | N9K76AA |
| | HP Single miniDP-to-DP Adapter Cable | 2MY05AA |
| Collaboration | HP UC Wired Headset | K7V17AA |
| Memory | HP 8GB 2666Mhz DDR4 | 4VN06AA |
| | HP 16GB 2666Mhz DDR4 | 4VN07AA |
| | HP 32GB 2666MHz DDR4 | 6NX83AA |
| | HP 8GB 2666MHz DDR4 ECC | 4UY11AA |
| | HP 16GB 2666MHz DDR4 ECC | 4UY12AA |
| Power - A/C Adapter | HP 200W Smart AC Adapter (4.5mm) | |
| | HP 200W Smart AC Adapter (4.5mm) | |
| Adapter Dongle | HP 7.4mm to 4.5mm DC Dongle | K0Q39AA |
| Security | HP Essential Combination Lock | T0Y16AA |
| | HP Keyed Cable Lock 10mm | T1A62AA |
| | HP Dual Head Keyed Cable Lock | T1A64AA |
| Storage - External | HP External USB DVDRW Drive | F2B56AA |
| Storage - SS M2 | HP 256GB PCIe 3x4 NVMe SSD (2280) | V3K66AA |
| | HP 512GB PCIe 3x4 NVMe DS SSD (2280) | V3K67AA |

title

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| Date of change: | Version History: | | Description of change: |
|------------------------|-------------------------|---------|---|
| September 11, 2020 | From v1 to v2 | Changed | Format |
| September 30, 2020 | From v2 to v3 | Changed | At A Glance, GRAPHICS, STORAGE AND DRIVES, SOFTWARE AND SECURITY, NETWORKING/COMMUNICATION, ENVIRONMENTAL DATA and Options and Accessories sections |
| October 20, 2020 | From v3 to v4 | Changed | Format |
| November 20, 2020 | From v4 to v5 | Changed | Format |
| December 1, 2020 | From v5 to v6 | Changed | Storage and Power sections |